



<b>Title of Change:</b>	Update to IPCN22093X to include mold compound change and update assembly location code on label from S to UB. Qualify Stars Microelectronics as alternative site for assembly & test and changes to leadframe, mold compound & die attach of SOT23-3 devices.													
<b>Proposed first ship date:</b>	18 June 2018													
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <marquita.jones@onsemi.com>													
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office.													
<b>Type of notification:</b>	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact &lt;PCN.Support@onsemi.com&gt;.</p>													
<b>Change Part Identification:</b>	<p>As material from different assembly sites cannot be combined into (1) reel, product from Stars will show ASSY LOC: UB (ASSY LOC = Assembly Location Code) on the label of the reel and box.</p> <p>Please see sample MPN on page 2 at the following link  <a href="http://www.onsemi.com/pub_link/Collateral/LABELRM-D.PDF">http://www.onsemi.com/pub_link/Collateral/LABELRM-D.PDF</a> to see the location of the ASSY LOC identifier.</p>													
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____													
<b>Change Sub-Category(s):</b>	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____													
<b>Sites Affected:</b>	ON Semiconductor Sites: None	External Foundry/Subcon Sites: Stars Microelectronics												
<b>Description and Purpose:</b>	<p>This is an update to IPCN22093X to include mold compound change and update assembly location code on label from S to UB.</p> <p>IPCN IPCN22093X was previously issued on December 2017 announcing the intent to qualify Stars Microelectronics as an alternative site for assembly and test with changes to leadframe and die attach for SOT23-3 devices to increase capacity of SOT23-3 devices. As a result, changes on the following will occur:</p> <table border="1"> <thead> <tr> <th></th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Leadframe</td> <td>AG SPOT 35x60 mils</td> <td>PPF+ME2 38x64 mils</td> </tr> <tr> <td>Die Attach</td> <td>EN4370K3</td> <td>ABLESTIK 8900NC</td> </tr> <tr> <td>Mold Compound</td> <td>G600FB</td> <td>G600</td> </tr> </tbody> </table>			Before Change Description	After Change Description	Leadframe	AG SPOT 35x60 mils	PPF+ME2 38x64 mils	Die Attach	EN4370K3	ABLESTIK 8900NC	Mold Compound	G600FB	G600
	Before Change Description	After Change Description												
Leadframe	AG SPOT 35x60 mils	PPF+ME2 38x64 mils												
Die Attach	EN4370K3	ABLESTIK 8900NC												
Mold Compound	G600FB	G600												

**Qualification Plan:****QV DEVICE NAME** TLV431BSN1T1G**RMS** 43362**PACKAGE** SOT23-3

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
RSH	JESD22- B106	Ta = 265C, 10 sec	
SD	JSTD002	Ta = 245C, 10 sec	

**QV DEVICE NAME** NCP431BVSNT1G**RMS** 43363**PACKAGE** SOT23-3

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
RSH	JESD22- B106	Ta = 265C, 10 sec	
SD	JSTD002	Ta = 245C, 10 sec	

Estimated date for qualification completion: 03 March 2018

**List of Affected Standard Parts:**

Part Number	Qualification Vehicle
TLV431ASN1T1G	TLV431BSN1T1G
TLV431BSN1T1G	TLV431BSN1T1G
NCP431ACSNT1G	NCP431BVSNT1G
NCP431AISNT1G	NCP431BVSNT1G
NCP431AVSNT1G	NCP431BVSNT1G
NCP431BCSNT1G	NCP431BVSNT1G
NCP431BISNT1G	NCP431BVSNT1G
NCP431BVSNT1G	NCP431BVSNT1G

**Appendix A: Changed Products**

DIKG : DIGI-KEY

Product	Customer Part Number	Qualification Vehicle
NCP431ACSNT1G		NCP431BVSNT1G
NCP431AISNT1G		NCP431BVSNT1G
NCP431AVSNT1G		NCP431BVSNT1G
NCP431BCSNT1G		NCP431BVSNT1G
NCP431BISNT1G		NCP431BVSNT1G
NCP431BVSNT1G		NCP431BVSNT1G
TLV431ASN1T1G		TLV431BSN1T1G
TLV431BSN1T1G		TLV431BSN1T1G